INTEGRATED
CIRCUITS

UNITRODE

UC1726
UC2726
UC3726

Isolated Drive Transmitter

FEATURES

- 750mA Output Drive, Source or Sink

- 8 to 35V Operation

- Transmits Drive Logic and Power through Low Cost Transformer

- Programmable Operating Frequency

- Up to 750kHz Operation

- Improved Output Control Algorithm Minimizes Output Jitter

- Fault Logic Monitors Isolated High Side IGBT Driver UC1727 for Faults

- User Programmable Fault Timing Screens False Fault Signals

- Shutdown Mode Disables On Chip Logic Reference for Low Standby Power

- Optional External Biasing of Logic Circuitry can Reduce Overall Power Dissipation

DESCRIPTION

The UC1726 Isolated Drive Transmitter, and its companion chip, the UC1727 Isolated High Side IGBT Driver, provide a unique solution to driving isolated power IGBTs. They are particularly suited to drive the high side devices on a high voltage H-bridge. The UC1726 device transmits the drive logic and drive power, along with transferring and receiving fault information with the isolated gate circuit using a low cost pulse transformer.

This drive system utilizes a duty cycle modulation technique that gives instantaneous response to the drive control transitions, and reliably passes steady state, or DC conditions. High frequency operation, up to 750kHz, allows the cost and size of the coupling transformer to be minimized.

The UC1726 can be powered from a single V_{CC} supply which internally generates a voltage reference for the logic circuitry. It can also be placed into a low power shutdown mode that disables the internal reference. The IC's logic circuitry can be powered from an external supply, V_L, to minimize overall power dissipation. Fault logic monitors the Isolated High Side IGBT Driver UC1727 for faults. Based on user defined timing, the UC1726 distinguishes valid faults, which it responds to by setting the fault latch pin. This also disables the gate drive information until the fault reset pin is toggled to a logic one.

The UC1726 operates over an 8 to 35 volt supply range. The typical V_{CC} voltage will be greater than 28 volts to be compatible with the UC1727. The undervoltage lockout circuitry of the Isolated High Side IGBT Driver UC1727 locks out the drive information during its undervoltage lockout.

BLOCK DIAGRAM
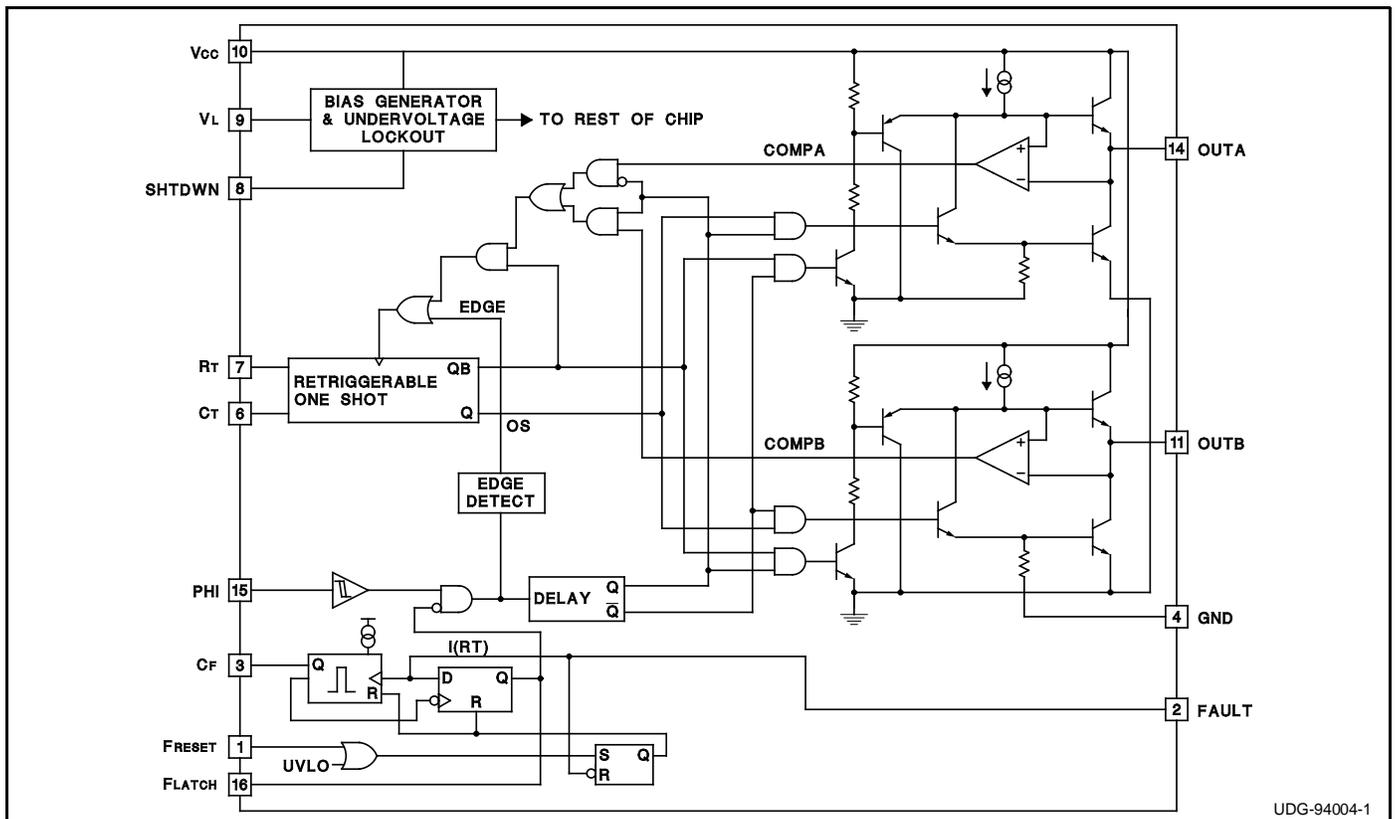
UDG-94004-1

ABSOLUTE MAXIMUM RATINGS

Supply Voltage V_{CC} 40V
Source/Sink Current (Pulsed) 1.5A
Source/Sink Current (Continuous) 1.0A
Output Voltage (pins 12, 14) . . . . −0.3 to (V_{CC} + 0.3)V
C_F, F_{RESET}, FAULT, SHTDWN,
F_{LATCH}, V_L, PHI, R_T . . . . −0.3 to 6.0V
C_T . . . . 1.0 to 6.0V
Operating Junction Temperature (Note 2) . . . . 150°C
Storage Temperature Range . . . . −65°C to 150°C
Lead Temperature (Soldering, 10 seconds) . . . . 300°C
*Note 1: All voltages are with respect to GND (Pin 2); all
currents are positive into, negative out of part.*

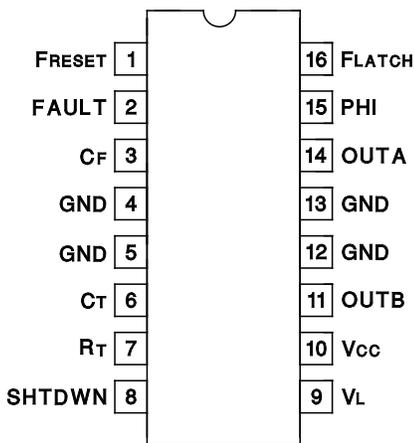## RECOMMENDED OPERATING CONDITIONS (Note 3)

Input Voltage . . . . +9 to +35.0V
Sink/Source Current (each output) . . . . 0 to 750mA
Timing Resistor . . . . 2.4k to 200kΩ
Timing Capacitor (C_T) . . . . 75pF to 2.0nF
Timing Capacitor (C_F) . . . . 75pF to 3.0nF
*Note 2: See Unitrode Integrated Circuits databook for information
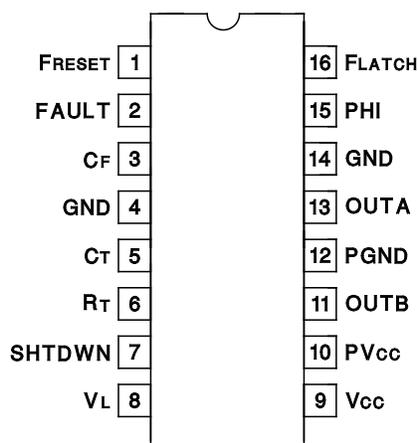regarding thermal specifications and limitations of
packages.*
*Note 3: Range over which the device is functional and parameter
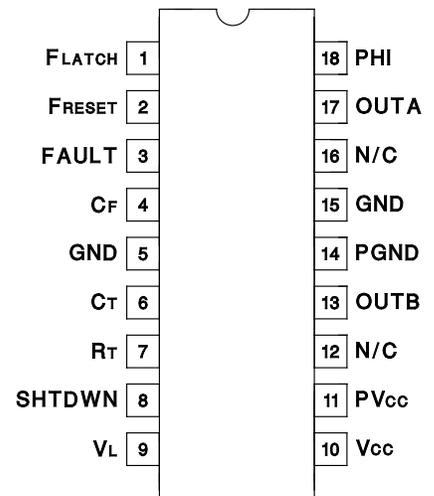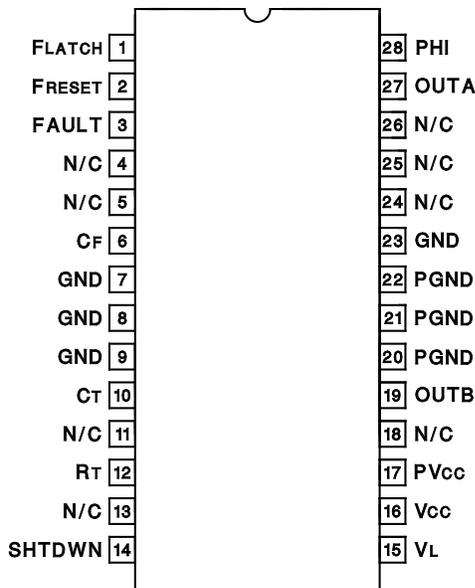limits are guaranteed.*

CONNECTION DIAGRAMS

DIL-16 (Top View)
N Package

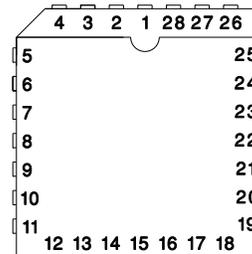|		
F_{RESET}	1	16 F_{LATCH}
FAULT	2	15 PHI
C_F	3	14 OUTA
GND	4	13 GND
GND	5	12 GND
C_T	6	11 OUTB
R_T	7	10 V_{CC}
SHTDWN	8	9 V_L

DIL-16 (Top View)
SP Package

F_{RESET}	1	16 F_{LATCH}
FAULT	2	15 PHI
C_F	3	14 GND
GND	4	13 OUTA
C_T	5	12 PGND
R_T	6	11 OUTB
SHTDWN	7	10 PV_{CC}
V_L	8	9 V_{CC}

DIL-18 (Top View)
J Package

F_{LATCH}	1	18 PHI
F_{RESET}	2	17 OUTA
FAULT	3	16 N/C
C_F	4	15 GND
GND	5	14 PGND
C_T	6	13 OUTB
R_T	7	12 N/C
SHTDWN	8	11 PV_{CC}
V_L	9	10 V_{CC}

SOIC-28 (Top View)
DWP Package

F_{LATCH}	1	28 PHI
F_{RESET}	2	27 OUTA
FAULT	3	26 N/C
N/C	4	25 N/C
N/C	5	24 N/C
C_F	6	23 GND
GND	7	22 PGND
GND	8	21 PGND
GND	9	20 PGND
C_T	10	19 OUTB
N/C	11	18 N/C
R_T	12	17 PV_{CC}
N/C	13	16 V_{CC}
SHTDWN	14	15 V_L

PLCC-28 (Top View)
QP Package

PACKAGE PIN FUNCTION	
FUNCTION	PIN
GND	1
C_T	2
N/C	3-4
R_T	5
SHTDWN	6
V_L	7
V_{CC}	8
N/C	9
PV_{CC}	10
OUTB	11
PGND	12-18
GND	19
OUTA	20
PHI	21
F_{LATCH}	22
F_{RESET}	23
FAULT	24
N/C	25
C_F	26
N/C	27
N/C	28

ELECTRICAL CHARACTERISTICS: Unless otherwise stated, V_{CC} = 20V, R_T = 4.32kΩ, C_T = 330pF and C_F = 2.2nF, no load on any output, and −55°C < T_A < 125°C for the UC1726, −40°C < T_A < 85°C for the UC2726, and 0°C < T_A < 70°C for the UC3726, T_A = T_J.

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Retriggerable one shot					
Initial Accuracy	T_J = 25°C	1.400	1.600	1.800	μsec
Temperature Stability	Over operating T_J	1.000		2.200	μsec
Voltage Stability	V_{CC} = 10 to 35V		0.2		%/V
Operating Frequency	L_{LOAD} = 1.5mH		170		kHz
PHI Input (Control Input)					
HIGH Input Voltage		2.0			V
LOW Input Voltage				0.8	V
HIGH Input Current			10		μA
LOW Input Current			-300	−600	μA
Delay to one shot			100	250	nsec
Delay to Output	C_T = 1.4V		250		nsec
Output Drivers					
Output Low Level	I_{SINK} = 20mA		0.3	0.5	V
	I_{SINK} = 400mA		0.5	2.6	V
Output High Level	I_{SOURCE} = −20mA		2.0	2.6	V
(volts below V_{CC})	I_{SOURCE} = −400mA		2.0	2.9	V
Rise and Fall Times	No load		30	60	nsec
Logic Voltage Reference					
V_L - Logic Voltage	Internal Voltage	4.20	4.40	4.60	V
Logic Supply Current	V_L = 4.75V to 5.25V, C_T = 1.4V		13.0	20.0	mA
Shut Down Circuit					
Logic Voltage - Off			0.5		V
High Input Current	V_{IH} = 2.4			-100	μA
Low Input Current	V_{IL} = 0.4			-20	μA
Fault Logic					
Fault Reset High Input Current	V_{IH} = 2.4			±5	μA
Fault Reset Low Input Current	V_{IL} = 0.4			-10	μA
Fault High Input Current	V_{IH} = 2.4			±5	μA
Fault Low Input Current	V_{IL} = 0.4			-60	μA
Fault Pulse Width	C_F = 330pF		3.0		μs
	C_F = 2.2nF		17.0		μs
Fault Latch, V_{OH}	I_{LOAD} = −1mA, Volts below V_L		1.3	1.8	V
Fault Latch, V_{OL}	I_{LOAD} = 1mA		0.25	0.5	V
Fault Latch, V_{OH}	I_{LOAD} = 0, Volts below V_L		0.3		V
Fault Latch, V_{OL}	I_{LOAD} = 0		0.2		V
Fault Reset Pulse Width			500		ns
UVLO					
Turn On Threshold			7.1		V
Total Supply Current					
Supply Current	C_T = 1.4V		22	40	mA
	C_T = 1.4V, V_L = 5.0V		12	20	mA
	C_T = 1.4V, Shutdown = 5.0V		2.5		mA

Refer to Typical Application on Page 5 and Application Note U-143A "New Chip Pair Provides Isolated Drive for High Voltage IGBTs"

PIN DESCRIPTIONS

C_F: The timing input to the fault logic. A capacitor is placed across the input of C_F and ground. The timing window is approximately $t = 2.1 C_F R_T$.

C_T: The connection to the timing capacitor that controls the operating frequency. A capacitor to ground is repetitively charged during the one shot pulse width. It is discharged when a comparator senses zero current in the primary side of the transformer. The one shot pulse width is consequently determined by the time it takes to charge the capacitor from a threshold voltage of $V_L/4$ to $V_L/2$. This pin must be tied to a capacitor. See Recommended Operating Conditions.

FAULT: This input to the fault logic initiates the user programmable timer. This time interval, specified by the capacitor on C_F, determines the validity of the fault. The pin is tied to a low cost optocoupler, and is high until the UC1727 sends drive information from the PHI pin through the transformer while the FAULT pin stays low. Once this pin goes high, it must stay high during the entire fault window to be accepted as a valid fault. A valid fault sets the F_{LATCH} pin high and prevents the transmitting of gate drive information until the F_{RESET} is toggled high. If fault logic is not used, the FAULT pin must be grounded.

F_{LATCH}: A valid fault sets this pin to a logic one and prevents the transmitting of gate drive information. The F_{LATCH} pin can only be reset by connecting the F_{RESET} to a logic 0.

F_{RESET}: The input to the fault logic that resets the fault logic latch (F_{LATCH}) and enables drive transmit data. This input must be low when powered up and stay low until after the fault latch has been set.

GND: The signal and power ground for the device. The power ground of the output transistor is isolated on the chip from the substrate ground which biases the remainder of the device.

OUTA: One output of the two totem pole outputs connected across the transformer primary winding. When PHI is high, the output toggles between 0.3V during the one shot charge time and approximately V_{CC} + 0.4V during the remainder of the period. When PHI is low the output toggles between V_{CC} - 2V during the one shot charge time and approximately $0.6 V_{CC}$ during the remainder of the period.

OUTB: One output of the two totem pole outputs connected across the transformer primary winding. When PHI is high, the output toggles between V_{CC} - 2V during the one shot charge time and approximately $0.6 V_{CC}$ during the remainder of the period. When PHI is low the output toggles between 0.3V during the one shot charge time and approximately V_{CC} + 0.4V during the remainder of the period.

PGND: This is the ground for the output transistors bonded in the 28 pin packages. On the sixteen pin packages it is bonded separately to the GND pin.

PHI: A logic control input to the isolated gate drive that changes the outputs as described above. This changes the duty cycle of the voltage wave form applied across the transformer. The Isolated High Side IGBT Driver UC1727 senses the different duty cycles as different drive commands.

PV_{CC}: This is the input voltage for the output transistors on the 28 pin package. On the sixteen pin packages it is bonded separately to the V_{CC} pin.

R_T: The input that sets the C_T and C_F capacitor currents with a resistor to ground. The voltage on R_T is approximately $0.3 V_L$. The resulting charge currents are: $I_{CT} = I_{CF} = V_L / 4 R_T$.

SHTDWN: This input shuts down the internal reference. A TTL logic one puts the UC1726 into a low standby current mode. This input has a pull down resistor on the chip to guarantee proper operation when left open. If an external logic voltage is applied to V_L, this shutdown feature cannot be used without bringing the external voltage source to zero volts.

V_{CC}: The input voltage that biases the outputs and the internal reference. It can vary between 8V to 35V. This supply pin will typically be greater than 28V to be compatible with the UC1727. In order to minimize power dissipation use an external logic supply, V_{CC} approximately 15V, and a step up transformer (N = 2).

V_L: The logic supply pin that biases all circuits except for the totem pole outputs. A bypass capacitor is recommended on this pin when left unconnected. The internal reference is approximately 4.4V. A 5.0V supply can be applied to this pin to assure minimum power dissipation. When an external supply higher than the V_L voltage is applied to this pin, the internal reference turns off.

OPERATING FREQUENCY:

The chip operating frequency is determined by the values of components connected to the R_T and C_T pins. A resistor connected between R_T and ground sets the charge current to $I_{CT} = V_L / 4R_T$. The operating frequency varies slightly depending on the V_{CC} and V_L voltages. The following equations approximate the one shot pulse width at operating frequency when $V_{CC} = 20V$.

$$T_{PW} = 1.1R_T(C_T + 50pF)$$

$$F_O = \frac{1}{3.3R_T(C_T + 50pF)}$$

The 50pF additional capacity represents internal chip capacitance at the C_T input.

TYPICAL APPLICATION

ISOLATION

UDG-94006

IF FAULT LOGIC NOT USED, GROUND FAULT PIN.
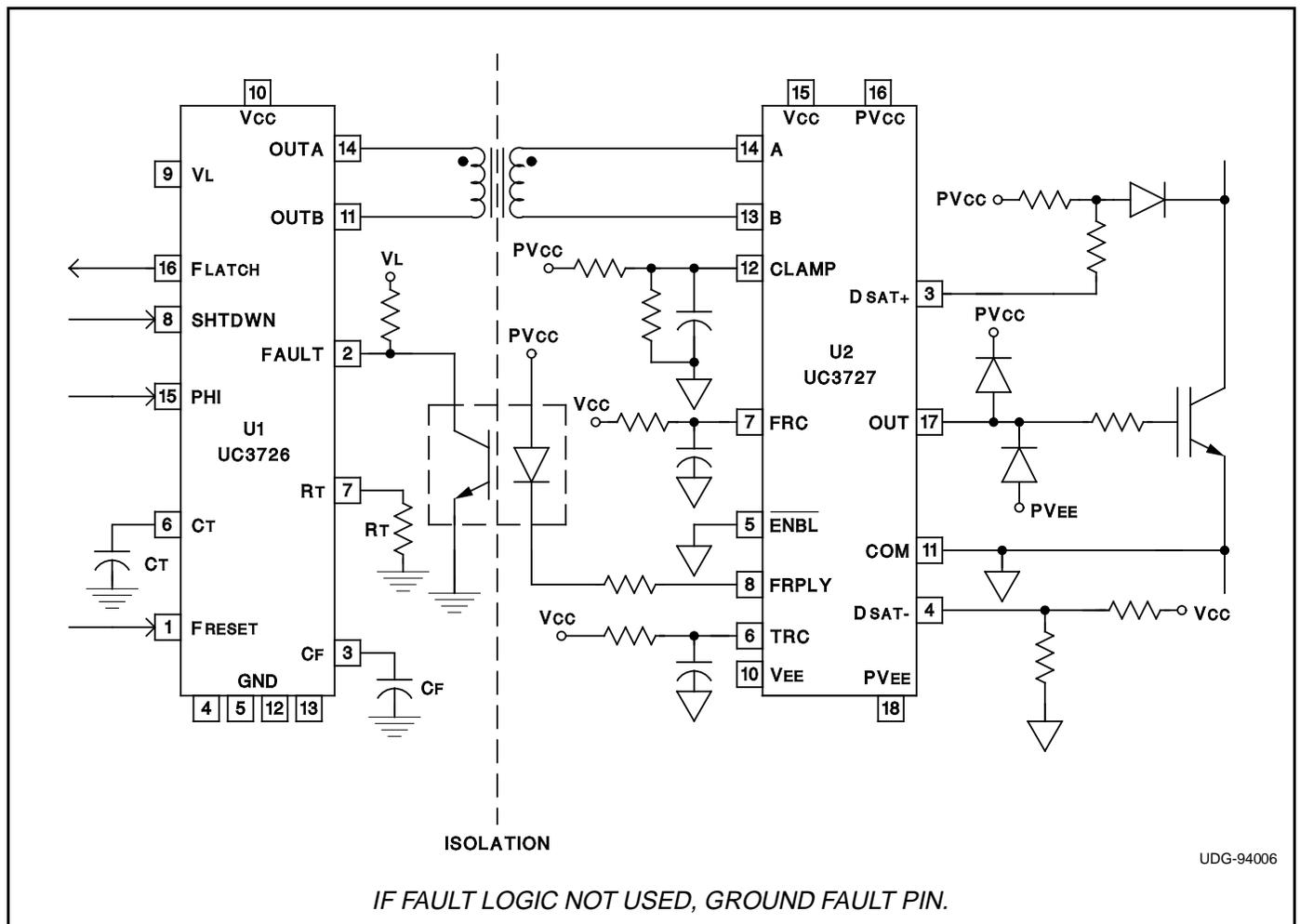
PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
UC2726DWP	OBSOLETE	SOIC	DW	28		TBD	Call TI	Call TI
UC2726DWPTR	OBSOLETE	SOIC	DW	28		TBD	Call TI	Call TI
UC2726N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
UC3726DWP	OBSOLETE	SOIC	DW	16		TBD	Call TI	Call TI
UC3726DWPTR	OBSOLETE	SOIC	DW	16		TBD	Call TI	Call TI
UC3726N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Mobile Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		